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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	e200z0h
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	CANbus, LINbus, SPI, UART/USART
Peripherals	DMA, POR, PWM, WDT
Number of I/O	37
Program Memory Size	192KB (192K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/spc560p34l1beaar

List of figures

Table 2. SPC560P34/SPC560P40 device comparison (continued)

Feature		SPC560P34 Full-featured	SPC560P40 Full-featured
eDMA (enhanced direct memory access) channels		16	
FlexCAN (controller area network)		1(1)	2(1),(2)
Safety port		No	Yes (via second FlexCAN module)
FCU (fault collection unit)		Yes	
CTU (cross triggering unit)		Yes	Yes
eTimer		1 (16-bit, 6 channels)	
FlexPWM (pulse-width modulation) channels		8 (capture capabity not supported)	8 (capture capability not supported)
Analog-to-digital converter (ADC)		1 (10-bit, 16 channels)	
LINFlex		2 (1 × Master/Slave, 1 × Master only)	2 (1 × Master/Slave, 1 × Master only)
DSPI (deserial serial peripheral interface)		2	3
CRC (cyclic redundancy check) unit		Yes	
Junction temperature sensor		No	
JTAG controller		Yes	
Nexus port controller (NPC)		Yes (Nexus Class 1)	
Supply	Digital power supply(3)	3.3 V or 5 V single supply with external transistor	
	Analog power supply	3.3 V or 5 V	
	Internal RC oscillator	16 MHz	
	External crystal oscillator	4–40 MHz	
Packages		LQFP64 LQFP100	
Temperature	Standard ambient temperature	–40 to 125 °C	

1. Each FlexCAN module has 32 message buffers.
2. One FlexCAN module can act as a safety port with a bit rate as high as 8 Mbit/s at 64 MHz.
3. The different supply voltages vary according to the part number ordered.

SPC560P34/SPC560P40 is available in two configurations having different features: Full-featured and airbag. *Table 3* shows the main differences between the two versions of the SPC560P40 MCU.

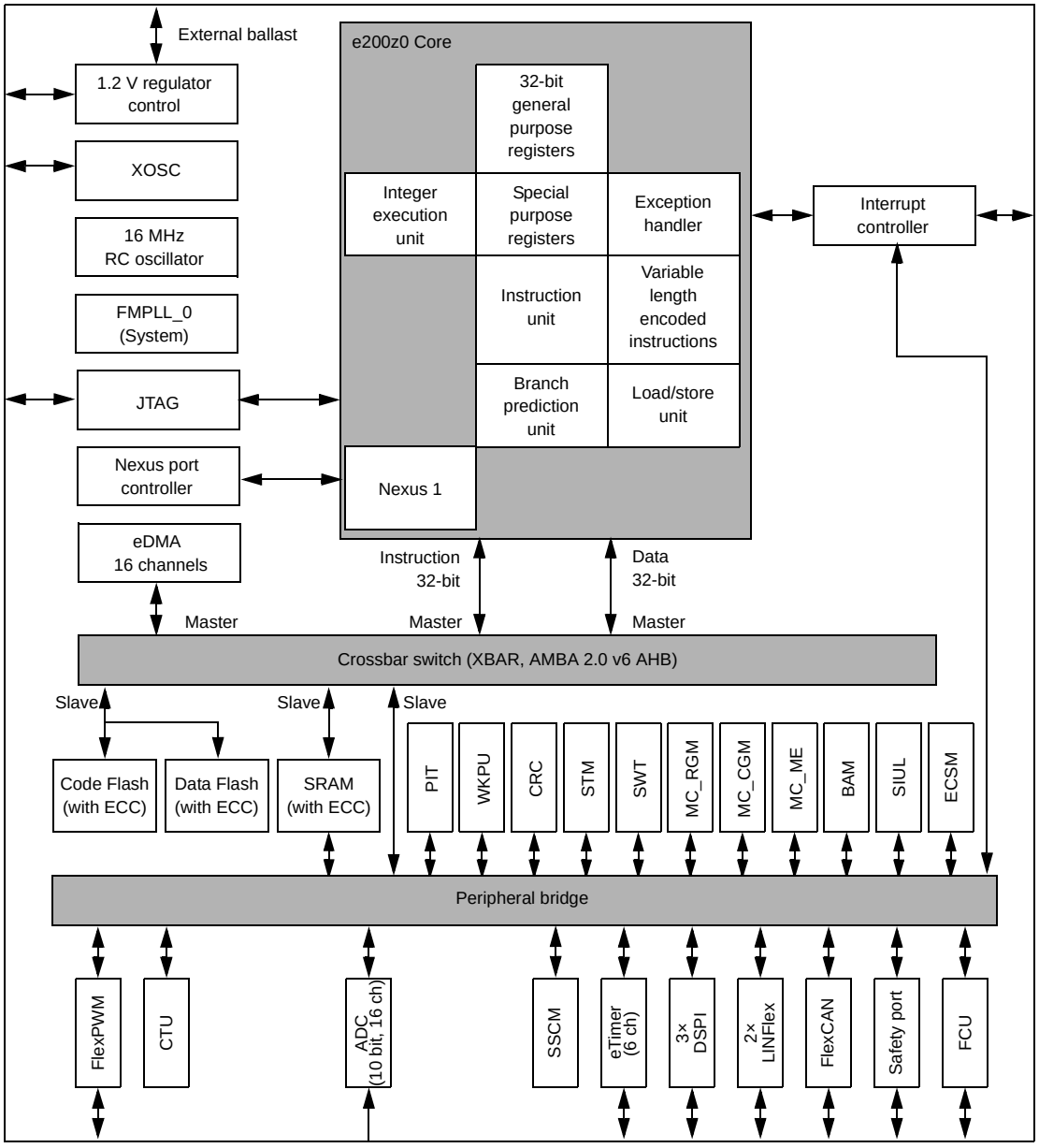
Table 3. SPC560P40 device configuration differences

Feature	Configuration	
	Airbag	Full-featured
SRAM (with ECC)	16 KB	20 KB
FlexCAN (controller area network)	1	2
Safety port	No	Yes (via second FlexCAN module)
FlexPWM (pulse-width modulation) channels	No	8 (capture capability not supported)
CTU (cross triggering unit)	No	Yes

1.4 Block diagram

Figure 1 shows a top-level block diagram of the SPC560P34/SPC560P40 MCU. *Table 2* summarizes the functions of the blocks.

Figure 1. Block diagram (SPC560P40 full-featured configuration)



Legend:

ADC	Analog-to-digital converter
BAM	Boot assist module
CRC	Cyclic redundancy check
CTU	Cross triggering unit
DSPI	Deserial serial peripheral interface
ECSM	Error correction status module
eDMA	Enhanced direct memory access
eTimer	Enhanced timer
FCU	Fault collection unit
Flash	Flash memory
FlexCAN	Controller area network
FlexPWM	Flexible pulse width modulation
FMPLL	Frequency-modulated phase-locked loop
INTC	Interrupt controller
JTAG	JTAG controller
LINFlex	Serial communication interface (LIN support)
MC_CGM	Clock generation module
MC_ME	Mode entry module
MC_PCU	Power control unit
MC_RGM	Reset generation module
PIT	Periodic interrupt timer
SIUL	System Integration unit Lite
SRAM	Static random-access memory
SSCM	System status and configuration module
STM	System timer module
SWT	Software watchdog timer
WKPU	Wakeup unit
XOSC	External oscillator
XBAR	Crossbar switch

The crossbar provides the following features:

- 3 master ports:
  - e200z0 core complex instruction port
  - e200z0 core complex Load/Store Data port
  - eDMA
- 3 slave ports:
  - Flash memory (Code and Data)
  - SRAM
  - Peripheral bridge
- 32-bit internal address, 32-bit internal data paths
- Fixed Priority Arbitration based on Port Master
- Temporary dynamic priority elevation of masters

1.5.3 Enhanced direct memory access (eDMA)

The enhanced direct memory access (eDMA) controller is a second-generation module capable of performing complex data movements via 16 programmable channels, with minimal intervention from the host processor. The hardware micro architecture includes a DMA engine which performs source and destination address calculations, and the actual data movement operations, along with an SRAM-based memory containing the transfer control descriptors (TCD) for the channels.

The eDMA module provides the following features:

- 16 channels support independent 8-, 16- or 32-bit single value or block transfers
- Supports variable-sized queues and circular queues
- Source and destination address registers are independently configured to either post-increment or to remain constant
- Each transfer is initiated by a peripheral, CPU, or eDMA channel request
- Each eDMA channel can optionally send an interrupt request to the CPU on completion of a single value or block transfer
- DMA transfers possible between system memories, DSPIs, ADC, FlexPWM, eTimer and CTU
- Programmable DMA channel multiplexer allows assignment of any DMA source to any available DMA channel with as many as 30 request sources
- eDMA abort operation through software

1.5.4 Flash memory

The SPC560P34/SPC560P40 provides 320 KB of programmable, non-volatile, flash memory. The non-volatile memory (NVM) can be used for instruction and/or data storage. The flash memory module is interfaced to the system bus by a dedicated flash memory controller. It supports a 32-bit data bus width at the system bus port, and a 128-bit read data interface to flash memory. The module contains four 128-bit wide prefetch buffers. Prefetch buffer hits allow no-wait responses. Normal flash memory array accesses are registered and are forwarded to the system bus on the following cycle, incurring two wait-states.

1.5.6 Interrupt controller (INTC)

The interrupt controller (INTC) provides priority-based preemptive scheduling of interrupt requests, suitable for statically scheduled hard real-time systems. The INTC handles 128 selectable-priority interrupt sources.

For high-priority interrupt requests, the time from the assertion of the interrupt request by the peripheral to the execution of the interrupt service routine (ISR) by the processor has been minimized. The INTC provides a unique vector for each interrupt request source for quick determination of which ISR has to be executed. It also provides a wide number of priorities so that lower priority ISRs do not delay the execution of higher priority ISRs. To allow the appropriate priorities for each source of interrupt request, the priority of each interrupt request is software configurable.

When multiple tasks share a resource, coherent accesses to that resource need to be supported. The INTC supports the priority ceiling protocol (PCP) for coherent accesses. By providing a modifiable priority mask, the priority can be raised temporarily so that all tasks which share the same resource can not preempt each other.

The INTC provides the following features:

- Unique 9-bit vector for each separate interrupt source
- 8 software triggerable interrupt sources
- 16 priority levels with fixed hardware arbitration within priority levels for each interrupt source
- Ability to modify the ISR or task priority: modifying the priority can be used to implement the priority ceiling protocol for accessing shared resources.
- 1 external high priority interrupt (NMI) directly accessing the main core and I/O processor (IOP) critical interrupt mechanism

1.5.7 System status and configuration module (SSCM)

The system status and configuration module (SSCM) provides central device functionality.

The SSCM includes these features:

- System configuration and status
  - Memory sizes/status
  - Device mode and security status
  - Determine boot vector
  - Search code flash for bootable sector
  - DMA status
- Debug status port enable and selection
- Bus and peripheral abort enable/disable

1.5.25 eTimer

The SPC560P34/SPC560P40 includes one eTimer module which provides six 16-bit general purpose up/down timer/counter units with the following features:

- Clock frequency same as that used for the e200z0h core
- Individual channel capability
  - Input capture trigger
  - Output compare
  - Double buffer (to capture rising edge and falling edge)
  - Separate prescaler for each counter
  - Selectable clock source
  - 0–100% pulse measurement
  - Rotation direction flag (quad decoder mode)
- Maximum count rate
  - External event counting: max. count rate = peripheral clock/2
  - Internal clock counting: max. count rate = peripheral clock
- Counters are:
  - Cascadable
  - Preloadable
- Programmable count modulo
- Quadrature decode capabilities
- Counters can share available input pins
- Count once or repeatedly
- Pins available as GPIO when timer functionality not in use

1.5.26 Analog-to-digital converter (ADC) module

The ADC module provides the following features:

Analog part:

- 1 on-chip analog-to-digital converter
  - 10-bit AD resolution
  - 1 sample and hold unit
  - Conversion time, including sampling time, less than 1 µs (at full precision)
  - Typical sampling time is 150 ns minimum (at full precision)
  - DNL/INL ±1 LSB
  - TUE < 1.5 LSB
  - Single-ended input signal up to 3.3 V/5.0 V
  - 3.3 V/5.0 V input reference voltage
  - ADC and its reference can be supplied with a voltage independent from V_{DDIO}
  - ADC supply can be equal or higher than V_{DDIO}
  - ADC supply and ADC reference are not independent from each other (both internally bonded to same pad)
  - Sample times of 2 (default), 8, 64 or 128 ADC clock cycles

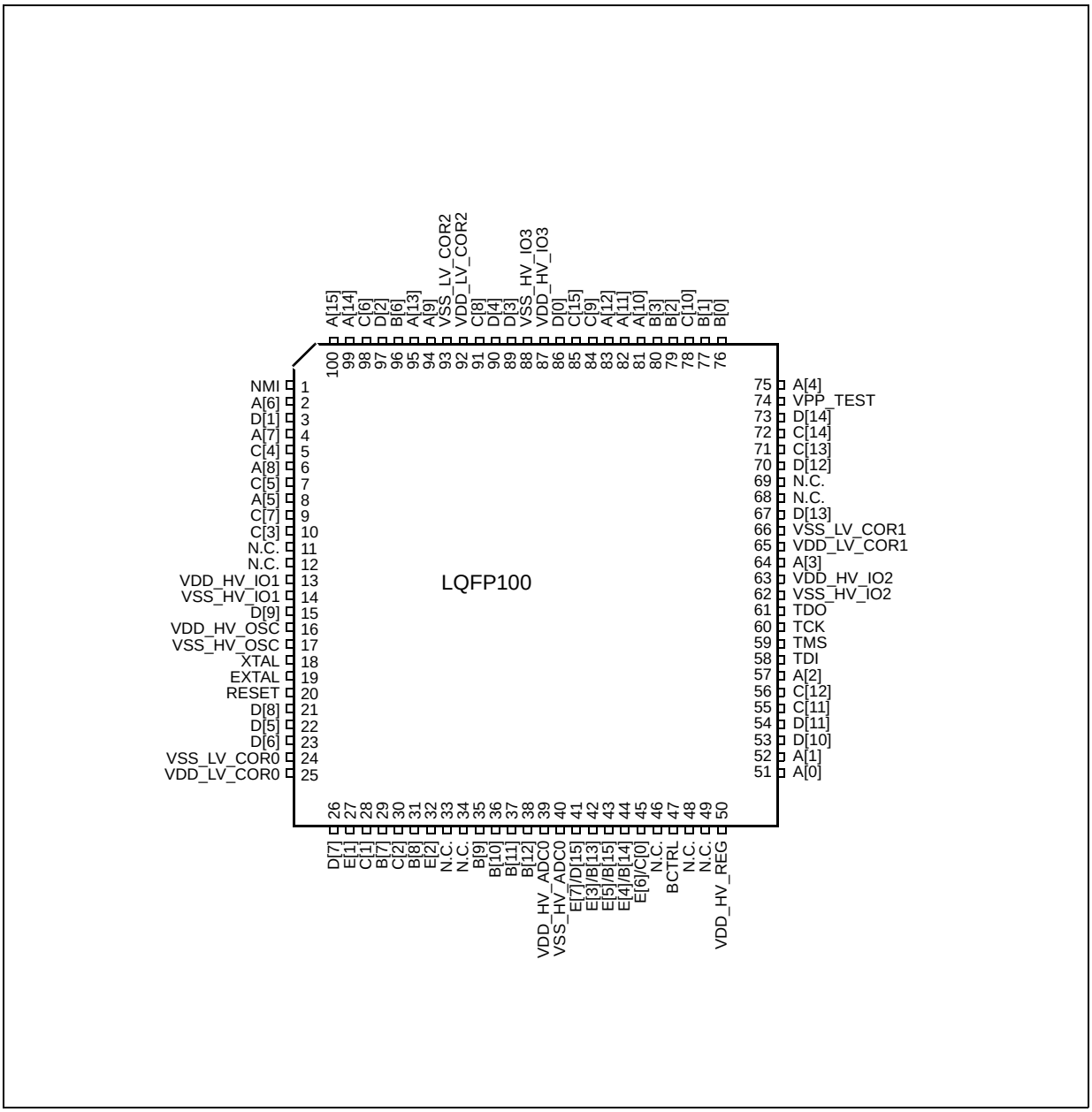


Figure 5. 100-pin LQFP pinout – Airbag configuration (top view)

Table 7. Pin muxing (continued)

Port pin	PCR register	Alternate function[1],[2]	Functions	Peripheral[3]	I/O direction[4]	Pad speed[5]		Pin	
						SRC = 0	SRC = 1	64-pin	100-pin
D[11]	PCR[59]	ALT0 ALT1 ALT2 ALT3	GPIO[59] B[0] — —	SIUL FlexPWM_0 — —	I/O O — —	Slow	Medium	—	54
D[12]	PCR[60]	ALT0 ALT1 ALT2 ALT3 —	GPIO[60] X[1] — — RXD	SIUL FlexPWM_0 — — LIN_1	I/O O — — I	Slow	Medium	45	70
D[13]	PCR[61]	ALT0 ALT1 ALT2 ALT3	GPIO[61] A[1] — —	SIUL FlexPWM_0 — —	I/O O — —	Slow	Medium	44	67
D[14]	PCR[62]	ALT0 ALT1 ALT2 ALT3	GPIO[62] B[1] — —	SIUL FlexPWM_0 — —	I/O O — —	Slow	Medium	46	73
D[15]	PCR[63]	ALT0 ALT1 ALT2 ALT3 — —	GPIO[63] — — — AN[10] emu. AN[4]	SIUL — — — ADC_0 emu. ADC_1[6]	Input only	—	—	—	41
Port E (16-bit)									
E[1]	PCR[65]	ALT0 ALT1 ALT2 ALT3 —	GPIO[65] — — — AN[4]	SIUL — — — ADC_0	Input only	—	—	18	27
E[2]	PCR[66]	ALT0 ALT1 ALT2 ALT3 —	GPIO[66] — — — AN[5]	SIUL — — — ADC_0	Input only	—	—	23	32
E[3]	PCR[67]	ALT0 ALT1 ALT2 ALT3 —	GPIO[67] — — — AN[6]	SIUL — — — ADC_0	Input only	—	—	30	42

Table 9. Absolute maximum ratings(1) (continued)

Symbol		Parameter	Conditions	Value		Unit
				Min	Max(2)	
I_{INJSUM}	S R	Absolute sum of all input currents during overload condition	—	–50	50	mA
T_{STG}	S R	Storage temperature	—	–55	150	°C
T_J	S R	Junction temperature under bias	—	–40	150	°C

1. Functional operating conditions are given in the DC electrical characteristics. Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond the listed maxima may affect device reliability or cause permanent damage to the device.
2. Absolute maximum voltages are currently maximum burn-in voltages.
3. The difference between each couple of voltage supplies must be less than 300 mV, $|V_{DD\_HV\_IOy} - V_{DD\_HV\_IOx}| < 300$ mV.
4. Guaranteed by device validation.
5. Minimum value of TV_{DD} must be guaranteed until $V_{DD\_HV\_REG}$ reaches 2.6 V (maximum value of V_{PORH})
6. Only when $V_{DD\_HV\_IOx} < 5.2$ V

Figure 6 shows the constraints of the different power supplies.

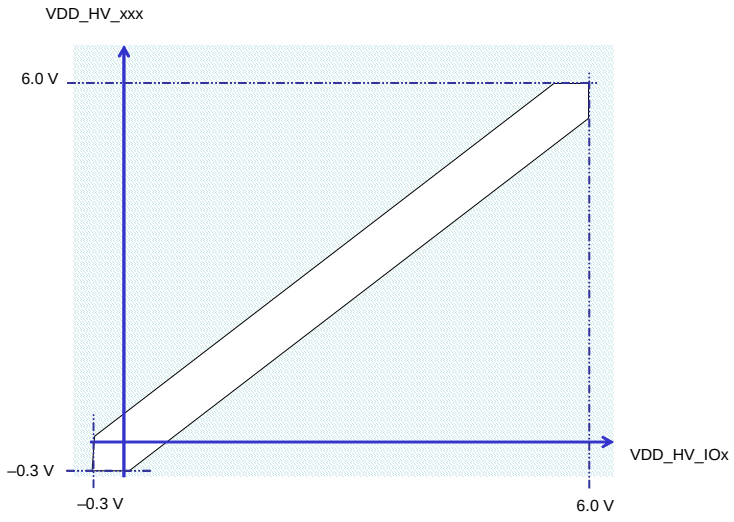


Figure 6. Power supplies constraints (–0.3 V ≤ $V_{DD\_HV\_IOx}$ ≤ 6.0 V)

The SPC560P34/SPC560P40 supply architecture allows the ADC supply to be managed independently from the standard V_{DD_HV} supply. *Figure 7* shows the constraints of the ADC power supply.

Table 11. Recommended operating conditions (3.3 V) (continued)

Symbol		Parameter	Conditions	Value		Unit
				Min	Max(1)	
$V_{DD\_HV\_REG}$	SR	3.3 V voltage regulator supply voltage	—	3.0	3.6	V
			Relative to $V_{DD\_HV\_IOx}$	$V_{DD\_HV\_IOx}$ – 0.1	$V_{DD\_HV\_IOx}$ + 0.1	
$V_{DD\_HV\_ADC0}$	SR	3.3 V ADC_0 supply and high reference voltage	—	3.0	5.5	V
			Relative to $V_{DD\_HV\_REG}$	$V_{DD\_HV\_REG}$ – 0.1	5.5	
$V_{SS\_HV\_ADC0}$	SR	ADC_0 ground and low reference voltage	—	0	0	V
$V_{DD\_LV\_REGCOR}$(3),(4)	CC	Internal supply voltage	—	—	—	V
$V_{SS\_LV\_REGCOR}$(3)	SR	Internal reference voltage	—	0	0	V
$V_{DD\_LV\_CORx}$(3),(4)	CC	Internal supply voltage	—	—	—	V
$V_{SS\_LV\_CORx}$(3)	SR	Internal reference voltage	—	0	0	V
T_A	SR	Ambient temperature under bias	f_{CPU} = 60 MHz	–40	125	°C
			f_{CPU} = 64 MHz	–40	105	°C

1. Full functionality cannot be guaranteed when voltage drops below 3.0 V. In particular, ADC electrical characteristics and I/Os DC electrical specification may not be guaranteed.
2. The difference between each couple of voltage supplies must be less than 100 mV, $|V_{DD\_HV\_IOy} - V_{DD\_HV\_IOx}| < 100$ mV.
3. To be connected to emitter of external NPN. Low voltage supplies are not under user control—they are produced by an on-chip voltage regulator—but for the device to function properly the low voltage grounds ($V_{SS\_LV\_xxx}$) must be shorted to high voltage grounds ($V_{SS\_HV\_xxx}$) and the low voltage supply pins ($V_{DD\_LV\_xxx}$) must be connected to the external ballast emitter.
4. The low voltage supplies ($V_{DD\_LV\_xxx}$) are not all independent.
   – $V_{DD\_LV\_COR1}$ and $V_{DD\_LV\_COR2}$ are shorted internally via double bonding connections with lines that provide the low voltage supply to the data flash memory module. Similarly, $V_{SS\_LV\_COR1}$ and $V_{SS\_LV\_COR2}$ are internally shorted.
   – $V_{DD\_LV\_REGCOR}$ and $V_{DD\_LV\_RECORx}$ are physically shorted internally, as are $V_{SS\_LV\_REGCOR}$ and $V_{SS\_LV\_CORx}$.

Figure 8 shows the constraints of the different power supplies.

3.6 Electromagnetic interference (EMI) characteristics

Table 13. EMI testing specifications

Symbol	Parameter	Conditions	Clocks	Frequency	Level (Typ)	Unit
V_{EME}	Radiated emissions	V_{DD} = 5.0 V; T_A = 25 °C Other device configuration, test conditions and EM testing per standard IEC61967-2	f_{OSC} = 8 MHz f_{CPU} = 64 MHz No PLL frequency modulation	150 kHz–150 MHz	11	dBµV
				150–1000 MHz	13	
				IEC level	M	—
			f_{OSC} = 8 MHz f_{CPU} = 64 MHz ±4% PLL frequency modulation	150 kHz–150 MHz	8	dBµV
				150–1000 MHz	12	
				IEC level	N	—
		V_{DD} = 3.3 V; T_A = 25 °C Other device configuration, test conditions and EM testing per standard IEC61967-2	f_{OSC} = 8 MHz f_{CPU} = 64 MHz No PLL frequency modulation	150 kHz–150 MHz	9	dBµV
				150–1000 MHz	12	
				IEC level	M	—
			f_{OSC} = 8 MHz f_{CPU} = 64 MHz ±4% PLL frequency modulation	150 kHz–150 MHz	7	dBµV
				150–1000 MHz	12	
				IEC level	N	—

3.7 Electrostatic discharge (ESD) characteristics

Table 14. ESD ratings(1),(2)

Symbol		Parameter	Conditions	Value	Unit
$V_{ESD(HBM)}$	S R	Electrostatic discharge (Human Body Model)	—	2000	V
$V_{ESD(CDM)}$	S R	Electrostatic discharge (Charged Device Model)	—	750 (corners)	V
				500 (other)	

1. All ESD testing is in conformity with CDF-AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits.
2. A device will be defined as a failure if after exposure to ESD pulses the device no longer meets the device specification requirements. Complete DC parametric and functional testing shall be performed per applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

3.8 Power management electrical characteristics

3.8.1 Voltage regulator electrical characteristics

The internal voltage regulator requires an external NPN ballast, approved ballast list availbale in *Table 15*, to be connected as shown in *Figure 10*. Capacitances should be placed on the board as near as possible to the associated pins. Care should also be taken to limit the serial inductance of the $V_{DD\_HV\_REG}$, BCTRL and $V_{DD\_LV\_CORx}$ pins to less than L_{Reg}. (refer to *Table 16*).

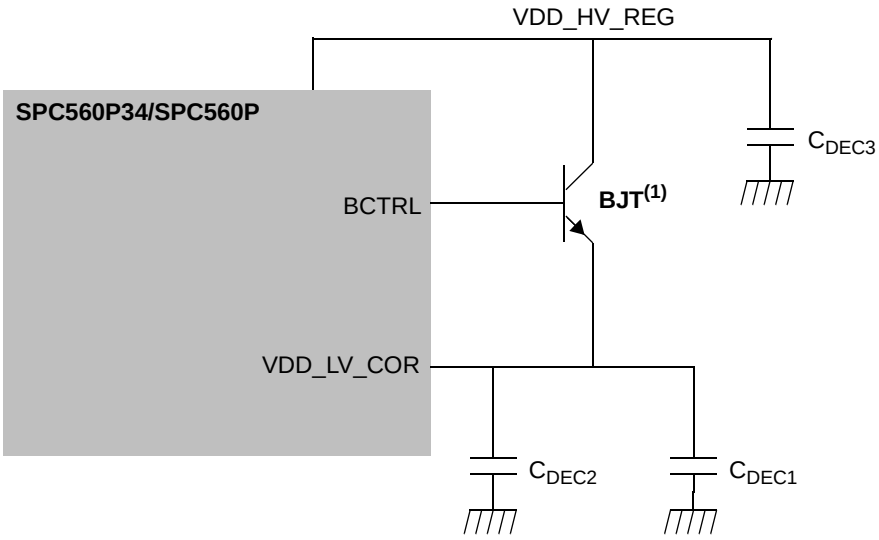
Note: The voltage regulator output cannot be used to drive external circuits. Output pins are to be used only for decoupling capacitance.

$V_{DD\_LV\_COR}$ must be generated using internal regulator and external NPN transistor. It is not possible to provide $V_{DD\_LV\_COR}$ through external regulator.

For the SPC560P34/SPC560P40 microcontroller, capacitor(s), with total values not below C_{DEC1}, should be placed between $V_{DD\_LV\_CORx}/V_{SS\_LV\_CORx}$ close to external ballast transistor emitter. 4 capacitors, with total values not below C_{DEC2}, should be placed close to microcontroller pins between each $V_{DD\_LV\_CORx}/V_{SS\_LV\_CORx}$ supply pairs and the $V_{DD\_LV\_REGCOR}/V_{SS\_LV\_REGCOR}$ pair . Additionally, capacitor(s) with total values not below C_{DEC3}, should be placed between the $V_{DD\_HV\_REG}/V_{SS\_HV\_REG}$ pins close to ballast collector. Capacitors values have to take into account capacitor accuracy, aging and variation versus temperature.

All reported information are valid for voltage and temperature ranges described in recommended operating condition, *Table 10* and *Table 11*.

Figure 10. Voltage regulator configuration



1. Refer to *Table 15*.

Table 15. Approved NPN ballast components

Part	Manufacturer	Approved derivatives(1)
BCP68	ON Semi	BCP68
	NXP	BCP68-25
	Infineon	BCP68-25
BCX68	Infineon	BCX68-10; BCX68-16; BCX-25
BC868	NXP	BC868

memory and 16 MHz RC oscillator needed during power-up phase and reset phase. When POWER_OK is low the associated modules are set into a safe state.

Figure 11. Power-up typical sequence

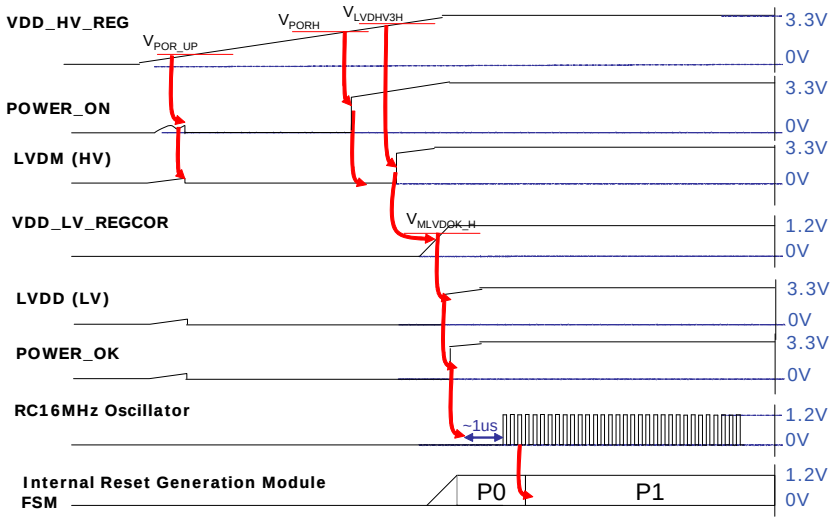
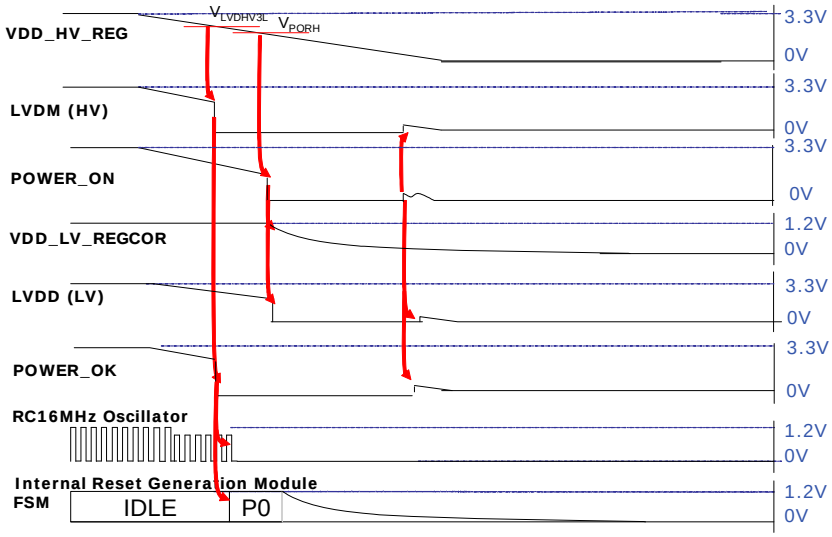


Figure 12. Power-down typical sequence



4. C_L includes device and package capacitance (C_{PKG} < 5 pF).
5. The configuration PAD3V5 = 1 when V_{DD} = 5 V is only transient configuration during power-up. All pads but RESET and Nexus output (MDOx, EVTO, MCKO) are configured in input or in high impedance state.

3.17.2 IEEE 1149.1 interface timing

Table 38. JTAG pin AC electrical characteristics

No.	Symbol		C	Parameter	Conditions	Value		Unit
						Min	Max	
1	t_{JCYC}	CC	D	TCK cycle time	—	100	—	ns
2	t_{JDC}	CC	D	TCK clock pulse width (measured at $V_{DD\_HV\_IOx}$/2)	—	40	60	ns
3	$t_{TCKRISE}$	CC	D	TCK rise and fall times (40%–70%)	—	—	3	ns
4	t_{TMSS}, t_{TDIS}	CC	D	TMS, TDI data setup time	—	5	—	ns
5	t_{TMSH}, t_{TDIH}	CC	D	TMS, TDI data hold time	—	25	—	ns
6	t_{TDOV}	CC	D	TCK low to TDO data valid	—	—	40	ns
7	t_{TDOI}	CC	D	TCK low to TDO data invalid	—	0	—	ns
8	t_{TDOHZ}	CC	D	TCK low to TDO high impedance	—	40	—	ns
9	t_{BSDV}	CC	D	TCK falling edge to output valid	—	—	50	ns
10	t_{BSDVZ}	CC	D	TCK falling edge to output valid out of high impedance	—	—	50	ns
11	t_{BSDHZ}	CC	D	TCK falling edge to output high impedance	—	—	50	ns
12	t_{BSDST}	CC	D	Boundary scan input valid to TCK rising edge	—	50	—	ns
13	t_{BSDHT}	CC	D	TCK rising edge to boundary scan input invalid	—	50	—	ns

Figure 22. JTAG test clock input timing

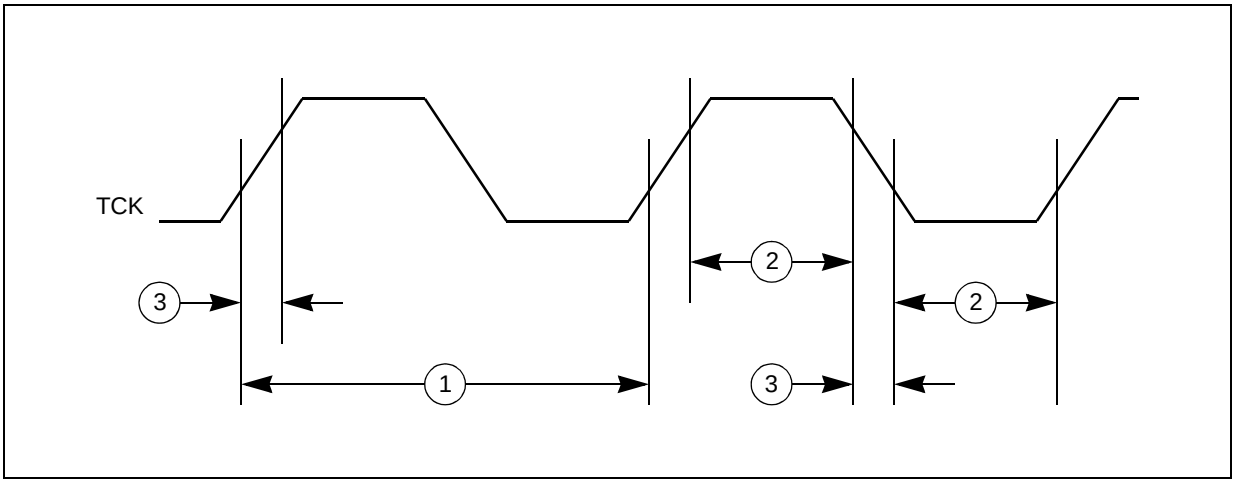
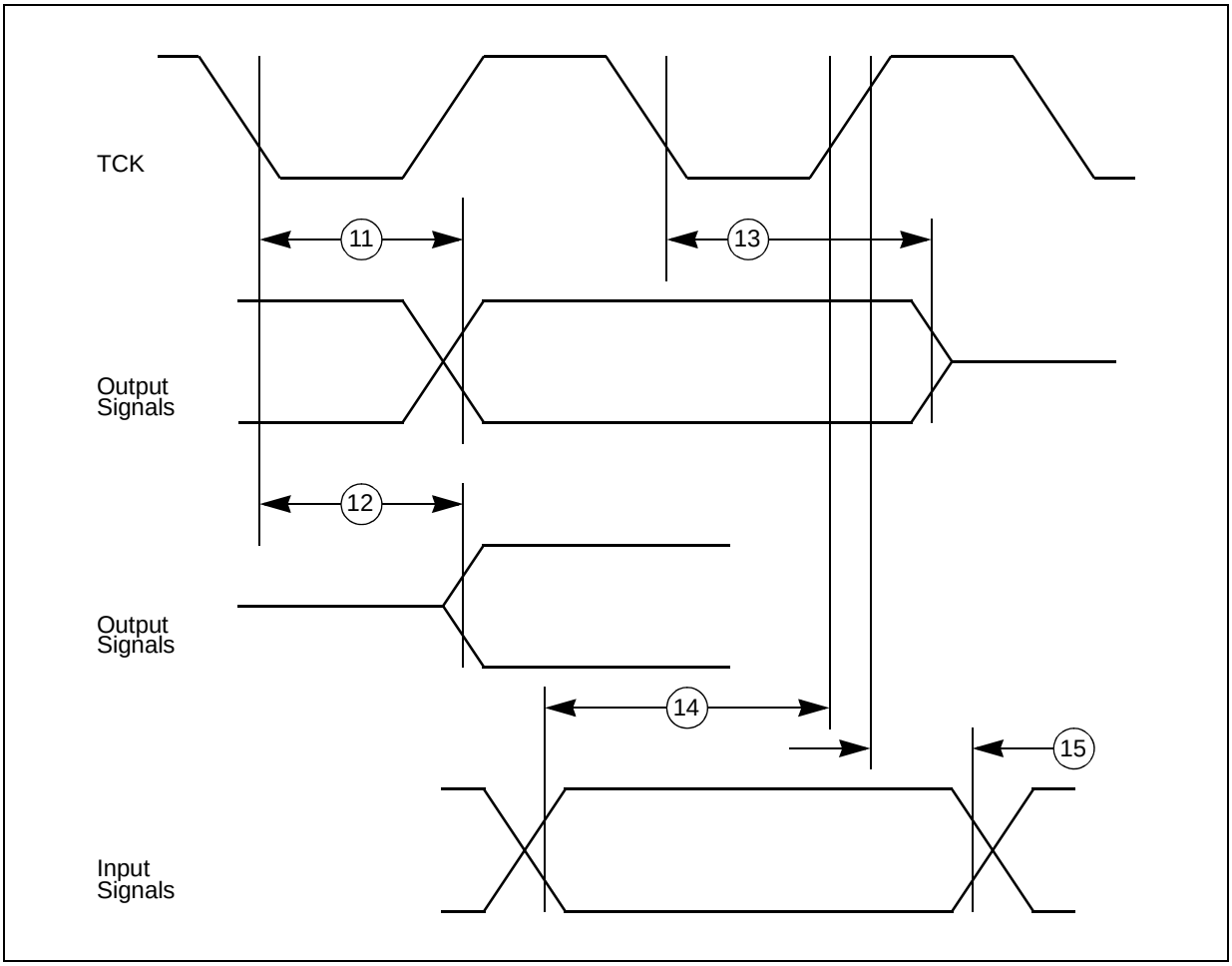


Figure 24. JTAG boundary scan timing



3.17.3 Nexus timing

Table 39. Nexus debug port timing(1)

No.	Symbol		C	Parameter	Value			Unit
					Min	Typ	Max	
1	t_{TCYC}	CC	D	TCK cycle time	4(2)	—	—	t_{CYC}
2	t_{NTDIS}	CC	D	TDI data setup time	5	—	—	ns
	t_{NTMSS}	CC	D	TMS data setup time	5	—	—	ns
3	t_{NTDIH}	CC	D	TDI data hold time	25	—	—	ns
	t_{NTMSH}	CC	D	TMS data hold time	25	—	—	ns
4	t_{TDOV}	CC	D	TCK low to TDO data valid	10	—	20	ns
5	t_{TDOI}	CC	D	TCK low to TDO data invalid	—	—	—	ns

1. All Nexus timing relative to MCKO is measured from 50% of MCKO and 50% of the respective signal.
2. Lower frequency is required to be fully compliant to standard.

Figure 25. Nexus output timing

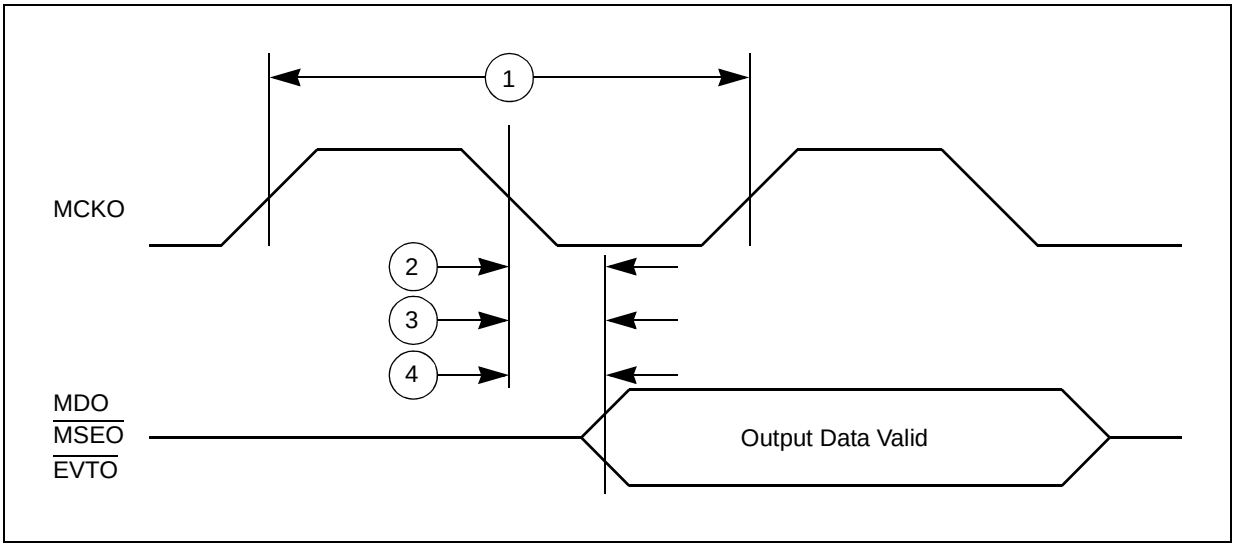


Figure 26. Nexus event trigger and test clock timing

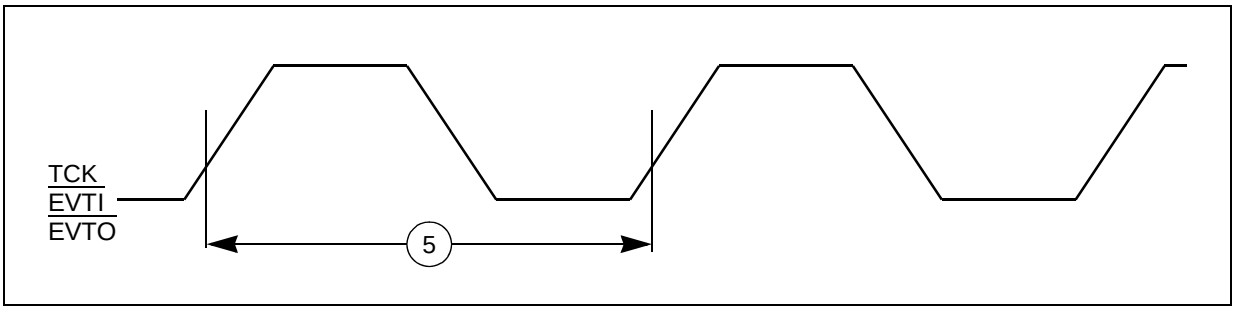
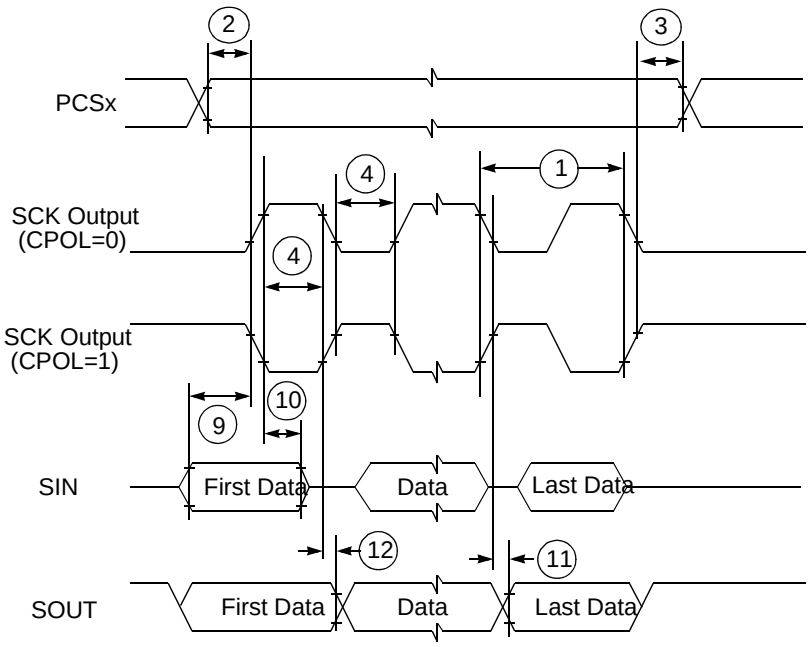


Table 41. DSPI timing(1) (continued)

No.	Symbol		C	Parameter	Conditions	Value		Unit
						Min	Max	
11	t_{SUO}	CC	D	Data valid (after SCK edge)	Master (MTFE = 0)	—	12	ns
					Slave	—	36	
					Master (MTFE = 1, CPHA = 0)	—	12	
					Master (MTFE = 1, CPHA = 1)	—	12	
12	t_{HO}	CC	D	Data hold time for outputs	Master (MTFE = 0)	–2	—	ns
					Slave	6	—	
					Master (MTFE = 1, CPHA = 0)	6	—	
					Master (MTFE = 1, CPHA = 1)	–2	—	

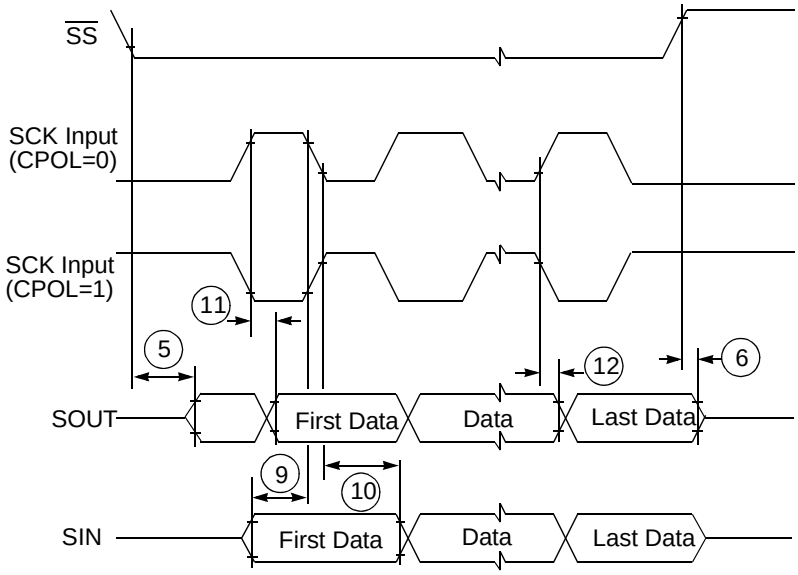
1. All timing are provided with 50 pF capacitance on output, 1 ns transition time on input signal

Figure 29. DSPI classic SPI timing – Master, CPHA = 0



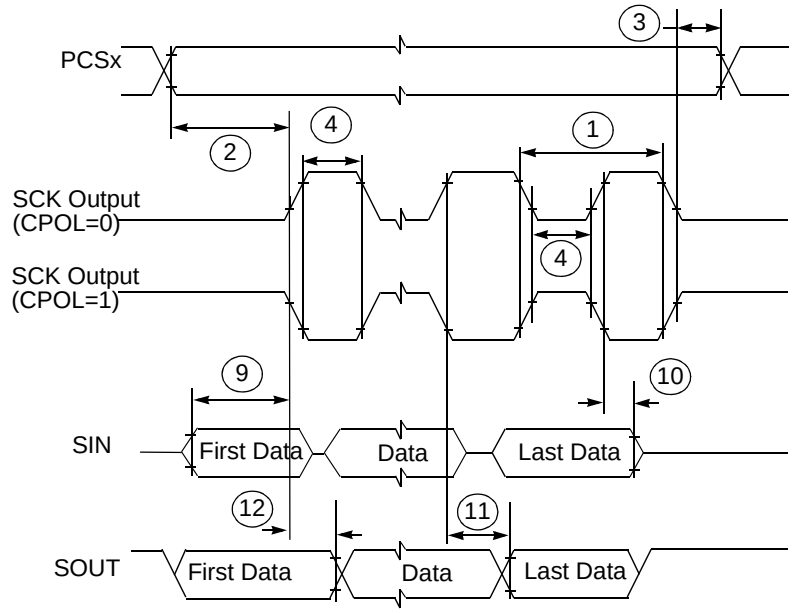
Note: Numbers shown reference *Table 41*.

Figure 32. DSPI classic SPI timing – Slave, CPHA = 1



Note: Numbers shown reference *Table 41*.

Figure 33. DSPI modified transfer format timing – Master, CPHA = 0



Note: Numbers shown reference *Table 41*.

Table 42. LQFP100 package mechanical data

Symbol	Dimensions					
	mm			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	—	—	1.600	—	—	0.0630
A1	0.050	—	0.150	0.0020	—	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	—	0.200	0.0035	—	0.0079
D	15.800	16.000	16.200	0.6220	0.6299	0.6378
D1	13.800	14.000	14.200	0.5433	0.5512	0.5591
D3	—	12.000	—	—	0.4724	—
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	—	12.000	—	—	0.4724	—
e	—	0.500	—	—	0.0197	—
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	—	1.000	—	—	0.0394	—
k	0.0°	3.5°	7.0°	0.0°	3.5°	7.0°
ccc[2]	0.08			0.0031		

1. Values in inches are converted from millimeters (mm) and rounded to four decimal digits.
2. Tolerance